

FEB. 19. 2003 9:58AM

LERNERDAVID

NO. 013

P.2

Electr #7
2/19/03

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail, in an envelope addressed to: Commissioner for Patents, Washington, DC 20231, on the date shown below.

Dated: July 10, 2002 Signature: 
(Marcus J. Miller)

FAX RECEIVED

FEB 19 2003

Docket No.: TESSERA 3.0-159 DIV
I.C. 2800
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
John W. Smith

Application No.: 09/942,363

Group Art Unit: 2825

Filed: August 29, 2001

Examiner: P. Greene

For: MICROELECTRONIC ASSEMBLIES WITH
COMPOSITE CONDUCTIVE ELEMENTS

Commissioner for Patents
Washington, DC 20231

RESPONSE

Dear Sir:

In response to the Official Action mailed June 28, 2002, Applicant hereby elects, with traverse, the claims of Group I, namely, claims 1-19, for examination in the present application.